

Claim 11. A support matrix for integrated semiconductors,
comprising:

a frame having at least one bonding channel with an edge
formed therein;

conductor track structures disposed on said frame;

 contacts, selected from the group consisting of bonding leads
and wires, connected to said conductor track structures and
disposed in said bonding channel, said contacts used for
connecting said conductor track structures to an integrated
circuit; and

a barrier formed along said edge, said barrier having a
parting agent disposed thereon for repelling a flowable
material from said bonding channel onto said frame and onto
said conductor track structures.
